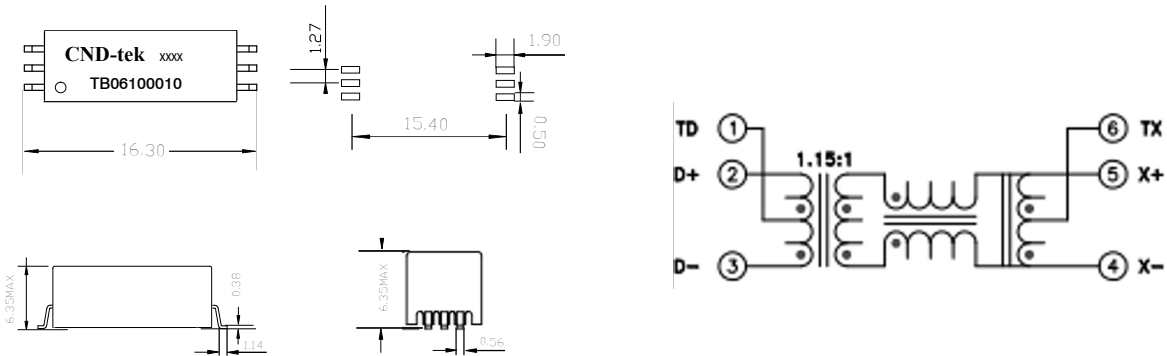


1. Low profile Surface Mount Packaging designed for Hi-Temp Reflow ProcessCompatible with various 10/100 Base-TX transceiver requiring 1.15:1 transmit and receive turns ratio
2. Compliant with IEEE 802.3at standard including baseline wander compensation specification of 350μH OCL when Biased at 8mA
3. Operating Temperature range: -40 °C TO +125 °C
4. Storage temperature range: -40 °C TO +125 °C



DIMENSIONS & SCHEMATICS

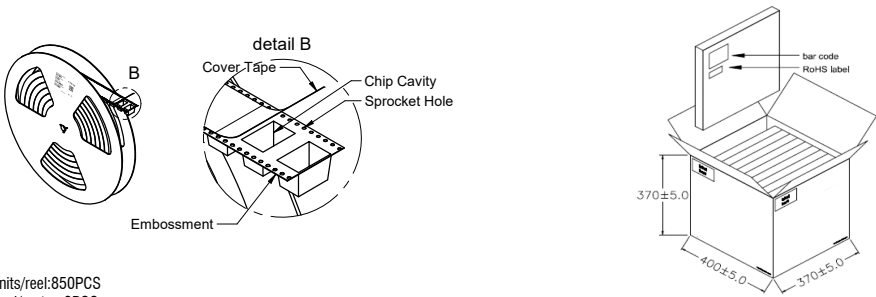


All 6 terminals must lie on a plane within .004mm of surface a after lead tinning

TECHNICAL SPECIFICATIONS

Inductance :	350 μH Min. @ 100 KHz, 100mV with 8mA DC Bias Lp(5-4)
Turns Ratio(±2%):	1.15CT:1CT
Insertion Loss:	-1.0dB Max. @ 0.3M-100MHz
Return Loss:	-12dB Min. @ 0.5M-40MHz -9dB Min. @ 40-60MHz -8dB Min.@ 60-80 MHz
CMRR:	-42dB Min.@ 0.3M-32MHz -33dB Min.@ 32M-100MHz
Isolation HI-POT:	1500Vrms 1mA 60Second or 1800Vrms 1mA 3Second

PACKING SPECIFICATION



1. units/reel:850PCS
2. reel/carton:3PCS
3. units/carton:2550PCS